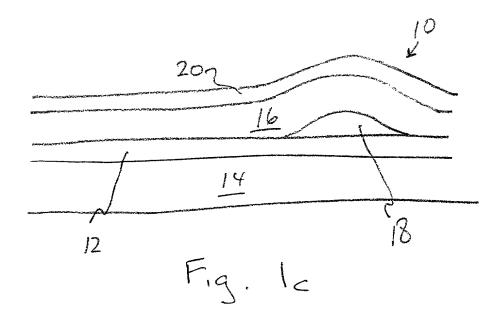
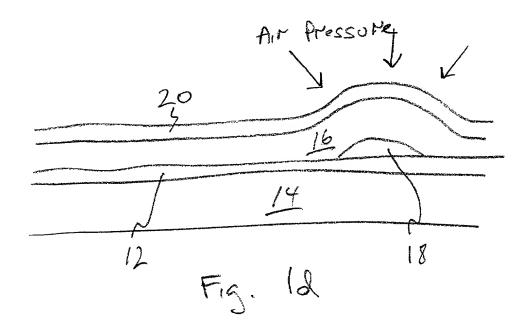
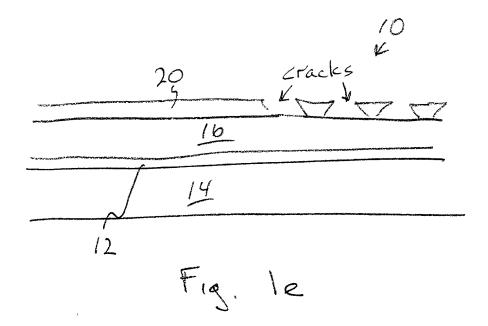
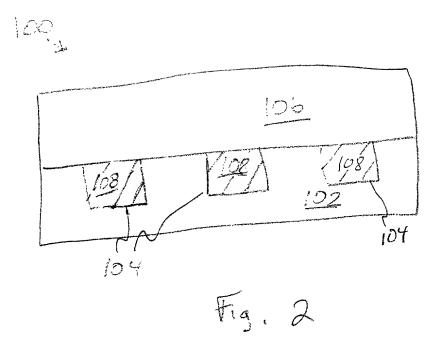


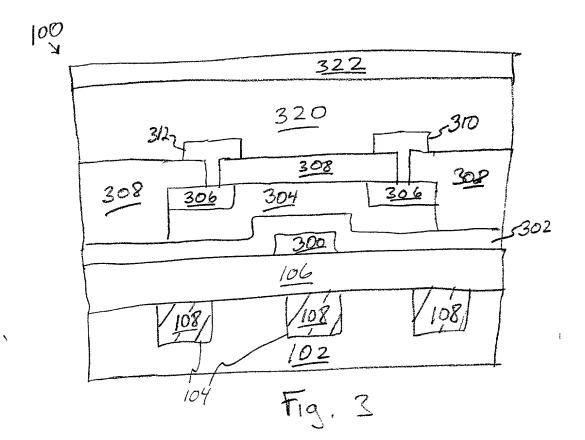
Fig. 16

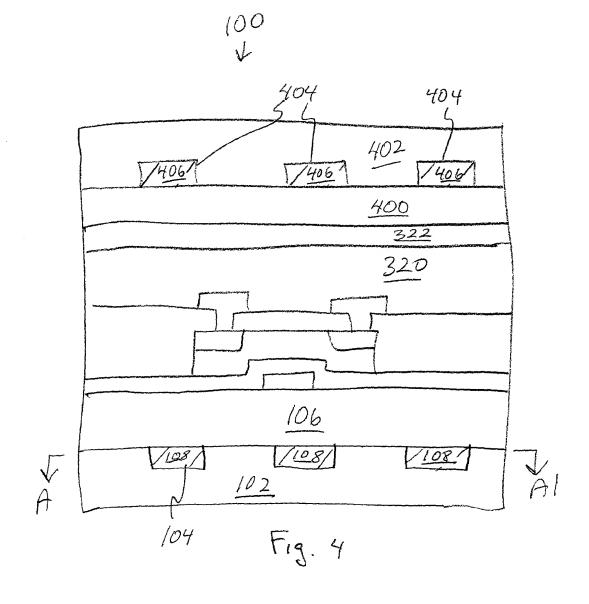


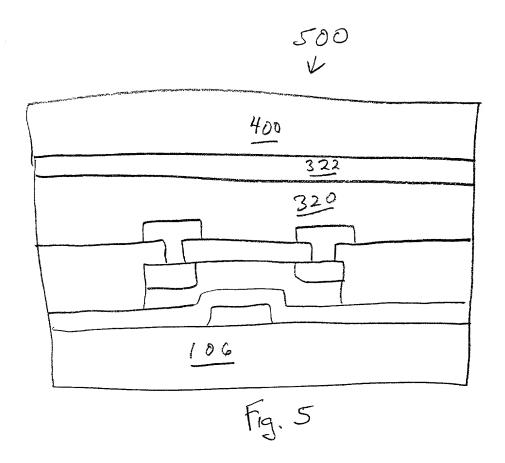


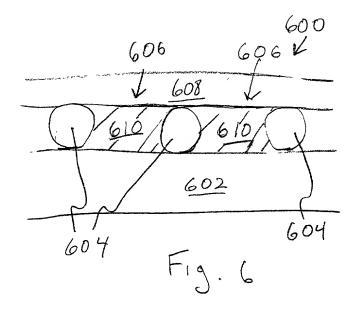












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Fig. 7

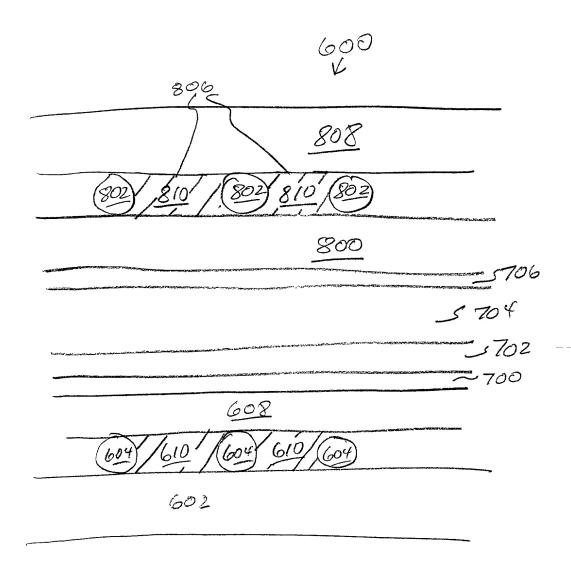


Fig. 8

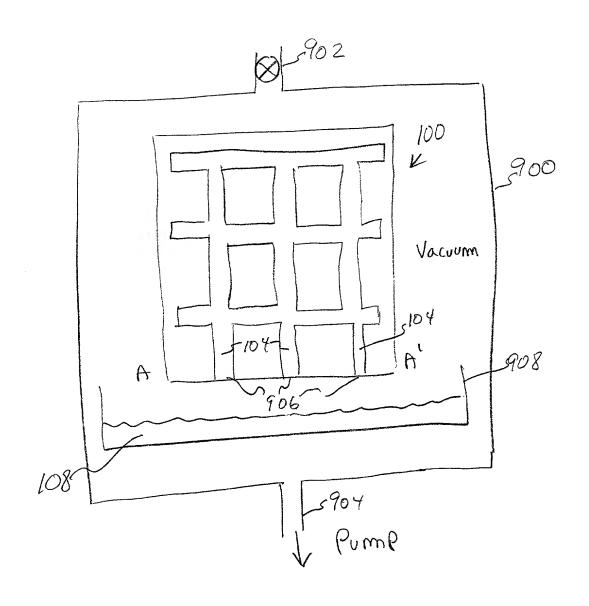


Fig. 9a

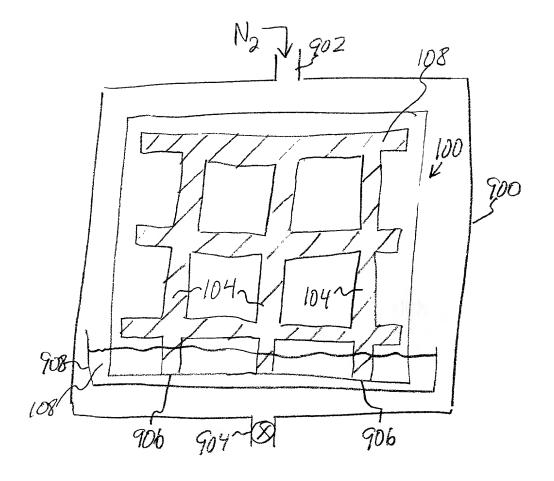


Fig. 96

51000 Start Fig. 10 100,2 forming rigid support substrate 1004 substrate flexible Shuind in Secting adhesive -1006a 1006b Vacuum SUPPLYING adhesive to trench mouth 1006c Pullins adhesive into Trench 1008 1010 Curing adhesive films Lepositina KC torming layer forming filter 20102 flexible Substra torming orming risid support ad hesive odhesive support substrate detaching

Fig. 11 1100 102 Misid support substrate Rorming flyxibe substrate insecting adhesive 75/108 TCreating Vacuum Supplying glue to spacer channels 1108cz/returning to ambient pressure 1108d2 Pulling adhesive into spacer channel Curing adhesive depositing JC films/112 forming LC layer ///
Horming Color filter forming flexible Substrat distributing spacers 1/20/122 forming risid support sobstrate adhesiver ingectina curing adhesive /5/1/26 detacting support substra